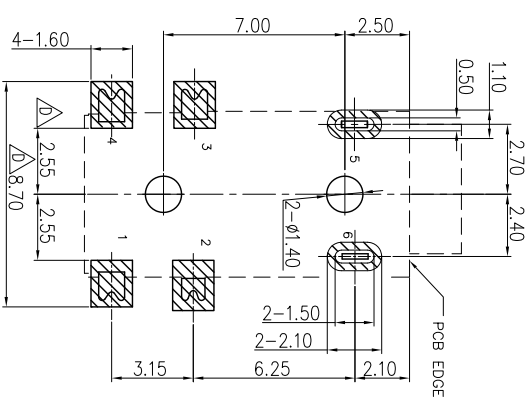
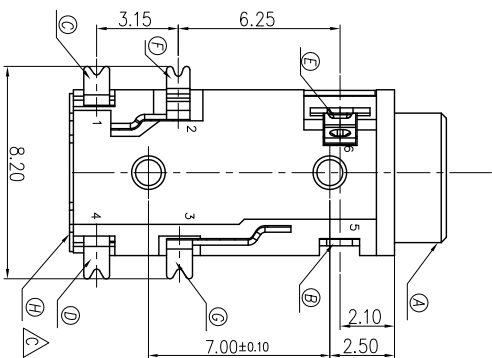
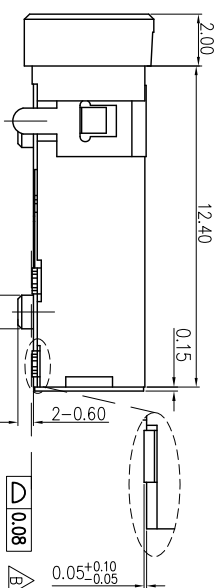
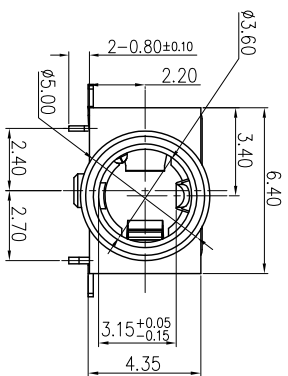
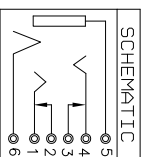


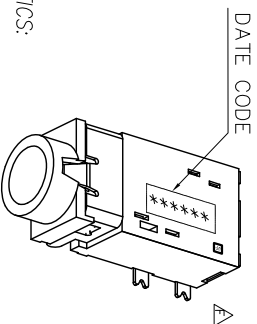
REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
D	ECN NO: C100448	Modify DIM	LONGJIANG	2010.12.14
E	ECN NO: C110387	Modify plating	LONGJIANG	2011.12.09
F	ECN: C130269	UPDATE DRAWING	TFY	2014.4.21



RECOMMENDED PCB LAYOUT
TOP VIEW (TOLERANCE: ±0.05)



3.5Ø 4POLE PLUG



- DATE CODE *****
- SPECIFICATIONS:
- ELECTRICAL CHARACTERISTICS:
 - RATING: 12V 1A
 - CONTACT RESISTANCE: 30mΩ MAX (INITIAL)
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC
 - MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE : 0.3~3.0 KGf
 - WITHDRAWAL FORCE : 0.3~3.0 KGf
 - LIFE TEST: 5,000 CYCLES MIN.
 - OTHER GENERAL SPEC. TO REFER "2SJ2269 SERIES SPEC".
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE SPEC.
 - GREEN PRODUCT IDENTIFICATION MARK ON JACK.
 - GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: **G.P. PASS**
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
H	COVER	1	SUS301-1/2H, 0.15t	
G	SHUNT-B	1	COPPER ALLOY 0.2t	Au 3μ Min.
F	SHUNT-A	1	COPPER ALLOY 0.2t	Au 3μ Min.
E	RING SPRING-B	1	COPPER ALLOY 0.2t	Au 3μ Min.
D	RING SPRING-A	1	COPPER ALLOY 0.2t	Gold flash on contact area And solder full over
C	TIP SPRING	1	COPPER ALLOY 0.2t	Nickel plated
B	EARTH SPRING	1	COPPER ALLOY 0.2t	Au 3μ Min.
A	BODY	1	HIGH TEMP. THERMOPLASTIC	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

X : ±0.5 X : ±2°

XX : ±0.3 XX : ±1°

XXX : ±0.2

Singatron Enterprise Co., Ltd.
信登企業股份有限公司

TITLE: 3.5Ø PHONE JACK

DWN: TFY 14/4/29 PART NO. 2SJ2269-002111

CHKD: ZUZ 14/4/29 SCALE 5:1 UNIT: mm

APVD: luo 14/4/29 SIZE: A3 SHEET: 10/1 REV: F

CUSTOMER COPY